

Claims

- [c1] A method of soldering a semiconductor part, comprising the steps of:
- printing a cream solder on a land on a circuit substrate;
 - mounting a semiconductor part in which a metal terminal is formed on a back surface and a side surface on said cream solder so that only a back surface portion of said metal terminal is in contact with said cream solder;
 - and
 - performing solder joining of said land and said semiconductor part by irradiating a side surface portion of said metal terminal with laser beams.
- [c2] The method of soldering a semiconductor part according to claim 1, wherein in said step of performing solder joining, cold air is supplied to a surface of said semiconductor part on which said metal terminal is not formed.
- [c3] The method of soldering a semiconductor part according to claim 2, wherein temperature conditions are set so that a difference between a temperature near said metal terminal which is irradiated with said laser beams and a temperature near the surface to which said cold air is supplied becomes within a prescribed temperature.

[c4] A mounted structure of a semiconductor part, wherein on a land of a circuit substrate, a semiconductor part having a metal terminal on a back surface and a side surface is mounted, via a cream solder printed on said land, so that almost all area of said land is opposed to a mounting surface of said semiconductor part and said land and said semiconductor part are solder jointed by irradiating a side surface portion of said metal terminal with laser beams.